

What is claimed is:

1. A method for electrostatically applying a powder adhesive formulation to a non-metallic  
5 substrate comprising:
  - a) forming a powder adhesive composition comprising a polymer:
  - b) applying an electrostatic charge to the powder;
  - c) depositing the charged powder onto a non-metallic substrate,wherein the electrostatically-applied adhesive is capable of being reactivated and used as an  
10 adhesive.
2. The method of claim 1 wherein said polymer is a natural polymer, a synthetic polymer,  
or a mixture thereof.
3. The method of claim 1 wherein said polymer comprises cationic functionality.
4. The method of claim 1 wherein said substrate is selected from the group consisting of  
15 wood, glass, paper, leather, paperboard, card board, corrugated board, cellulose, plastics,  
wovens, and non-woven materials.
5. A method for bonding a non-metallic substrate to another substrate comprising:
  - a) forming a powder adhesive formulation comprising a polymer:
  - b) applying an electrostatic charge to the powder adhesive formulation;
  - 20 c) depositing the charged powder onto a non-metallic substrate, activating said powder  
adhesive formulation, and contacting the activated adhesive-containing non-metallic  
substrate with a second substrate;
  - d) allowing the adhesive between the two substrates to cure, producing bonded  
substrates.
- 25 6. The method of claim 5 wherein the steps of step c) are performed in the order of activating  
the powder adhesive at the same time as it is being deposited onto a non-metallic substrate,  
then contacting the activated adhesive-containing non-metallic substrate to a second  
substrate.
7. The method of claim 5 wherein the steps of step c) are performed in the order of depositing  
30 the charged powder onto a non-metallic substrate, contacting the adhesive-containing non-

metallic substrate to a second substrate, then activating said powder adhesive formulation.

8. The method of claim 5 wherein said second substrate is a non-metallic substrate.

9. The method of claim 5 wherein said second substrate is a metallic substrate.

10. The method of claim 5 wherein said activation of the powder adhesive comprises

5 contacting the adhesive with a water mist, heat, or radiation.

11. A powder adhesive coated non-metallic substrate comprising a non-metallic substrate having directly deposited thereon by electrostatic forces, a powder adhesive capable of being activated to exhibit adhesive properties.

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